



2026 Second Quarter Earnings Conference

2Q 2026

Phoenix Silicon International Corporation



Safe Harbor Notice

PSI's statements of its current expectations are forward-looking statements subject to significant risks and uncertainties, and actual results may differ materially from those contained in the forward-looking statements.

Information as to factors that could cause actual results to vary can be found in PSI's Annual or Quarterly Reports filed with the Taiwan Stock Exchange Corporation (TWSE), and in other documents that PSI may file with or submit to the TWSE from time to time.

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The figures in this presentation are prepared under IFRS.

PSI At a Glance

CORPORATE PROFILE



COMPANY

1997

Founded

2018

Listed



CAPITAL

\$1,790M

Paid-in Capital

(Jun. 30, 2026)

\$45,700M

Market Cap.

(Aug. 31, 2026)



PEOPLE

910

Employees

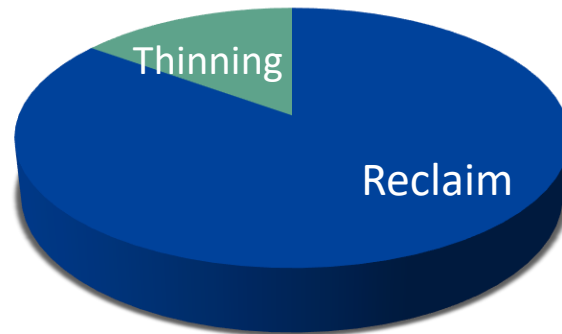
(Jun. 30, 2026)

BUSINESS UNITS

WW No.1

MEOL Foundry

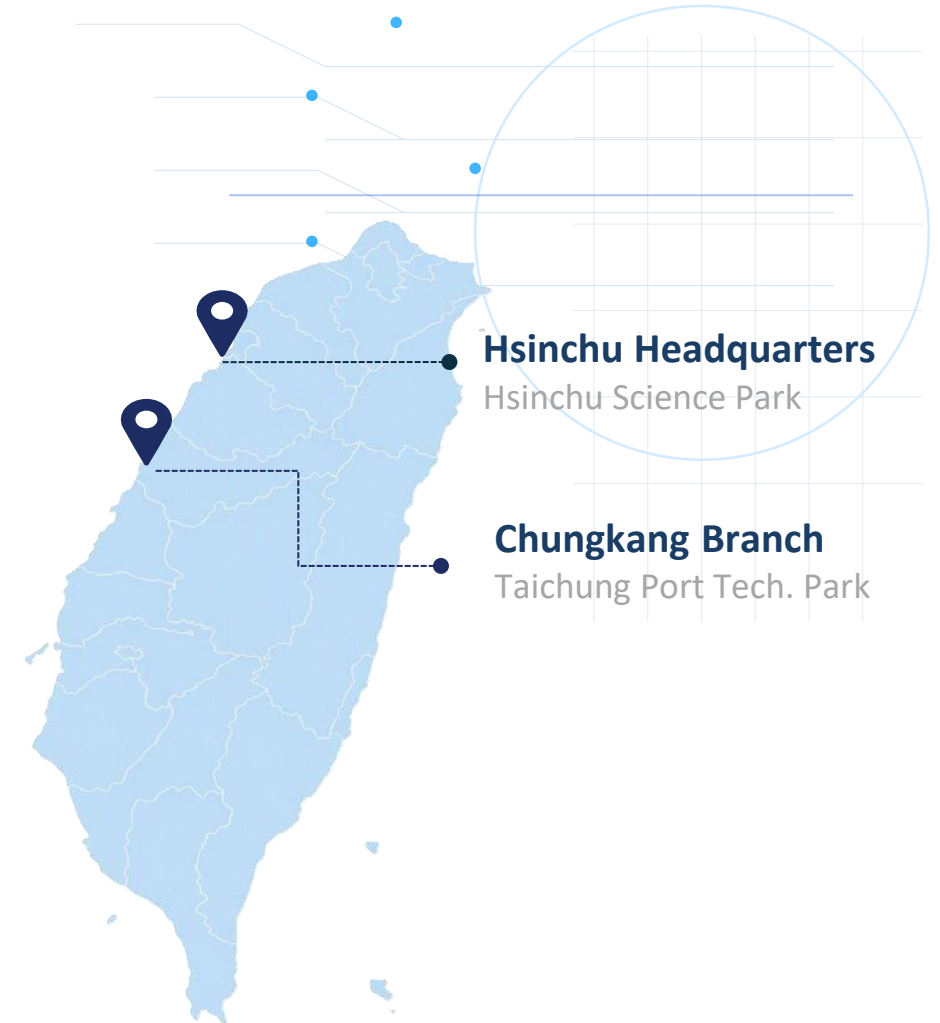
Wafering Thinning



WW No.1

Reclaim Services

Quantity & Quality



PSI Competitive Edge

01 THE MOST REWARDABLE



Leading Technology Innovator

- Advanced process capability drives margin content growth.
- Technology leadership delivers PSI's customer's best value.

Customer's Value Up

02 THE MOST SCALABLE



AI-Enabling Automation Pioneer

- Automation and AI improve PSI's productivity and execution consistency.
- Scalable capacity build-out supports sustainable growth in advance.

Operating Leverage

03 THE MOST ECO-FRIENDLY

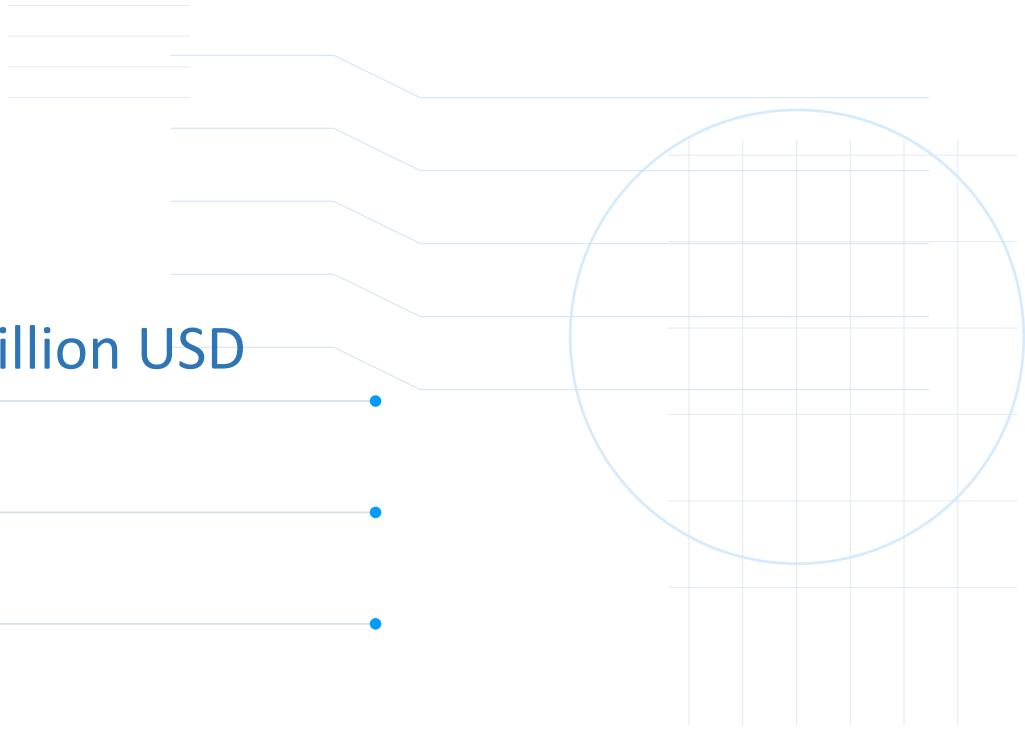


Recycle, Reuse & Reduction Executor

- Reclaim wafer business embeds ESG culture into PSI's operating core.
- Resource circulation efficiency improves long-term margin gains.

ESG Margin Added

Agenda



01 AI Driving Semiconductor Outpace 2 Trillion USD

02 | Growth Strategy

Pillar I Wafer Reclaim

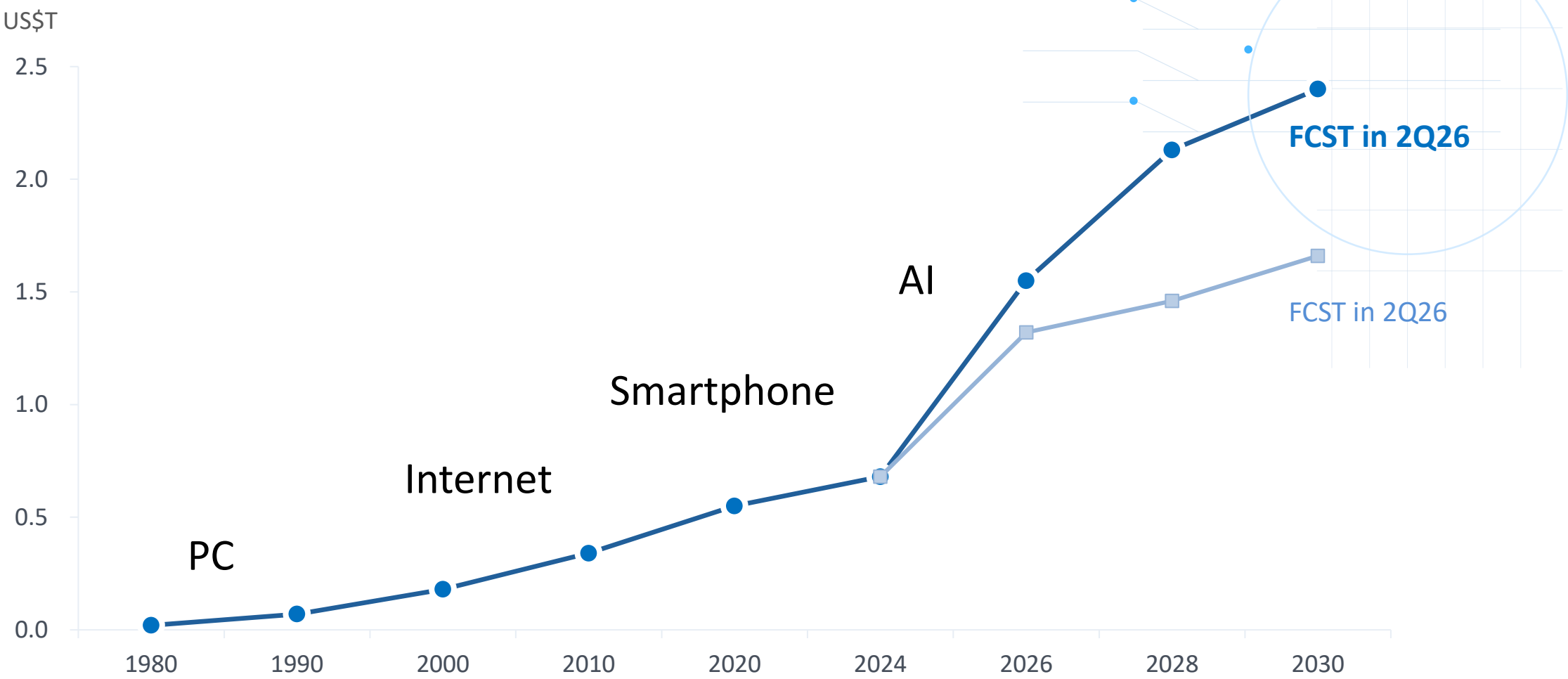
Pillar II Wafer Thinning

Pillar III Advanced Materials Solutions

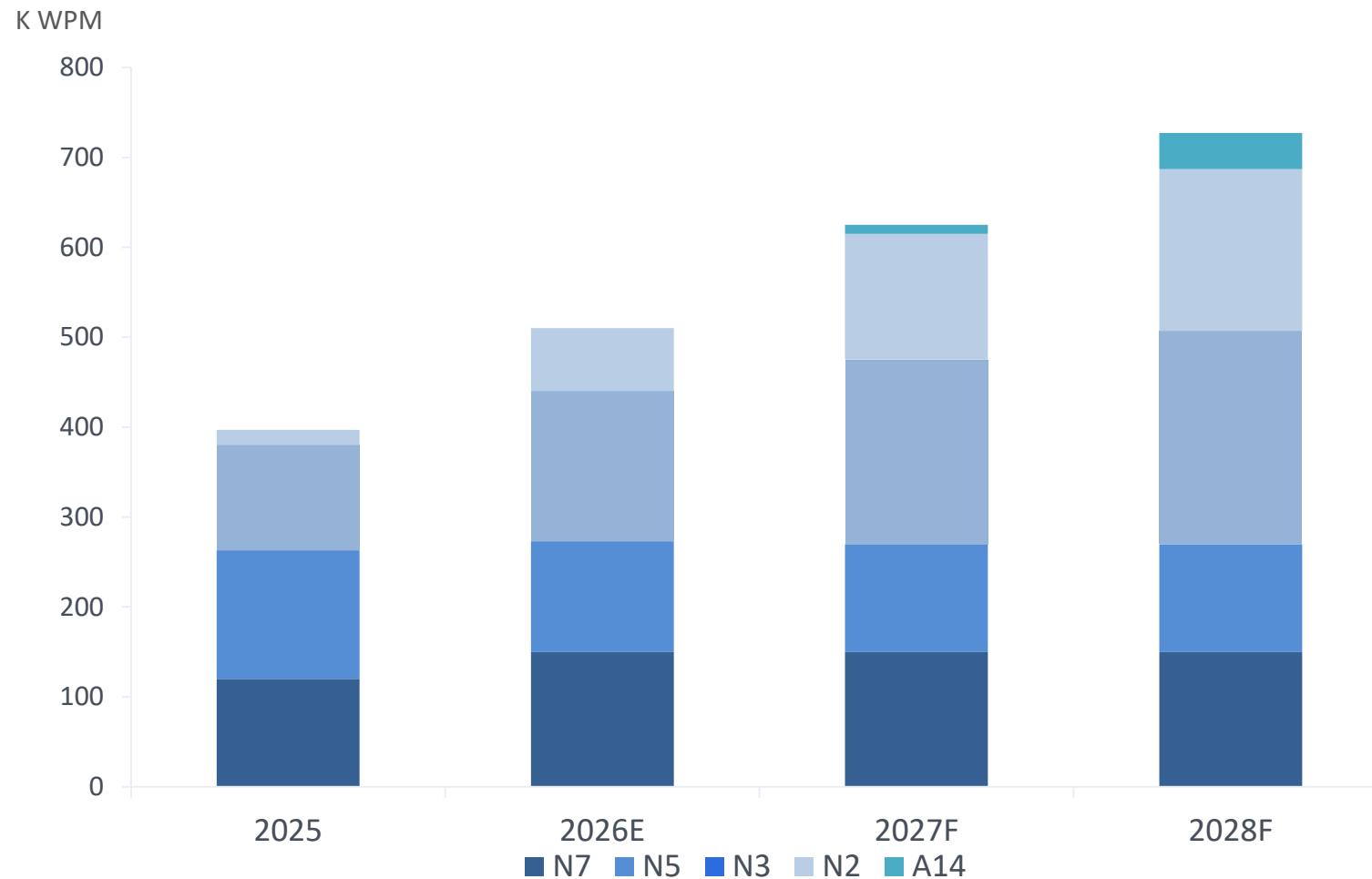
03 | Financial Performance

04 | Key Summary

AI Driving Semiconductor Outpace 2 Trillion USD



Accelerating Advanced Node Expansion

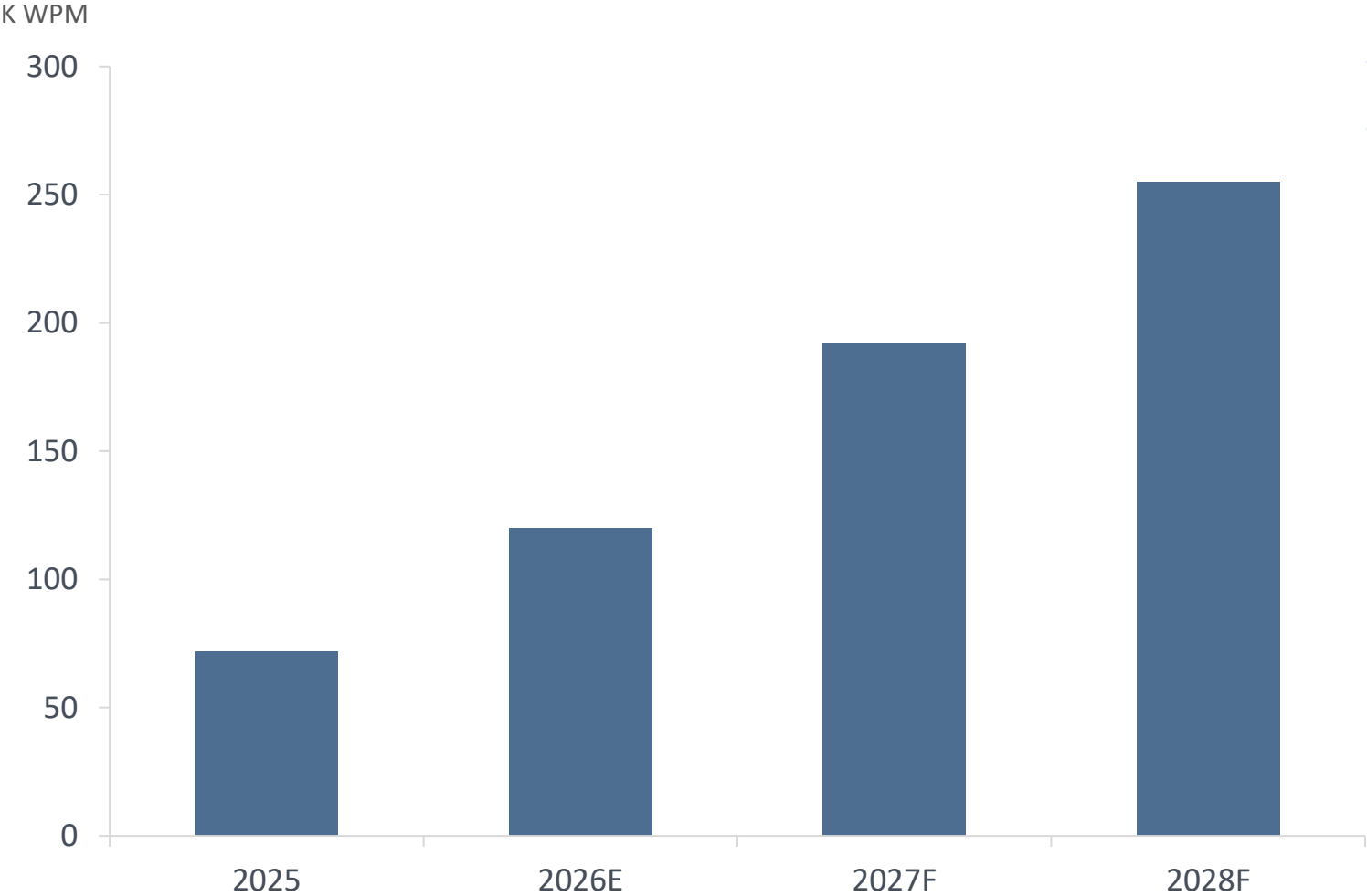


AI drives capacity expansion

Sub-5nm
CAGR 27.7%

- CPO-EIC 7nm
- Optical DSP sub-7nm
- HBM base die sub-5nm
- AISC sub-5nm
- GPU sub-4nm

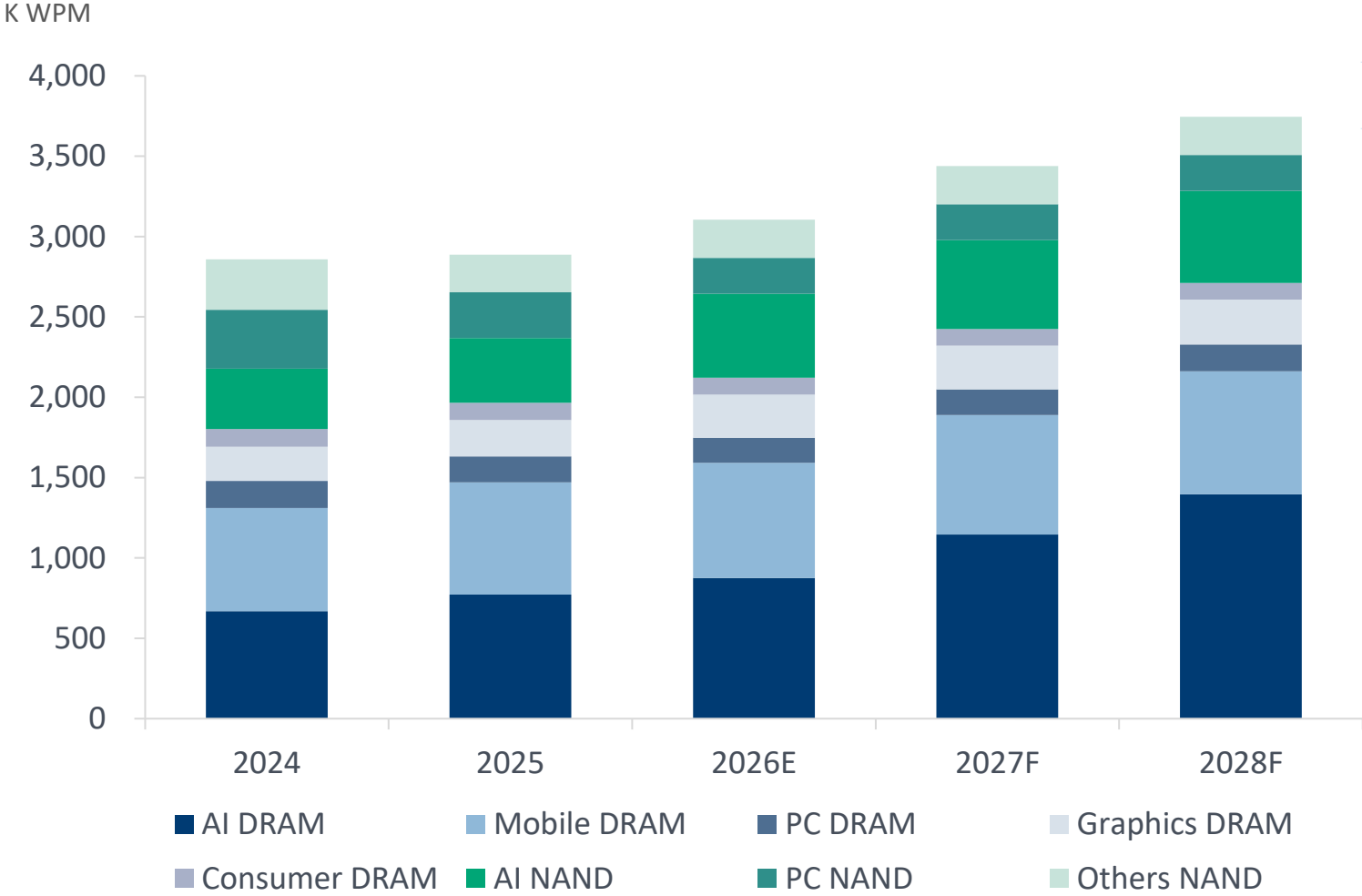
Revving Up Advanced Packaging



2.5 Packaging capacity
CAGR 52.5%

- 2.5 Packaging capacity growth underscores the intensity of AI-driven advanced packaging demand.

Memory For AI Surging



Total CAGR
5.1%

AI DRAM CAGR
46.8%

AI NAND CAGR
22.5%

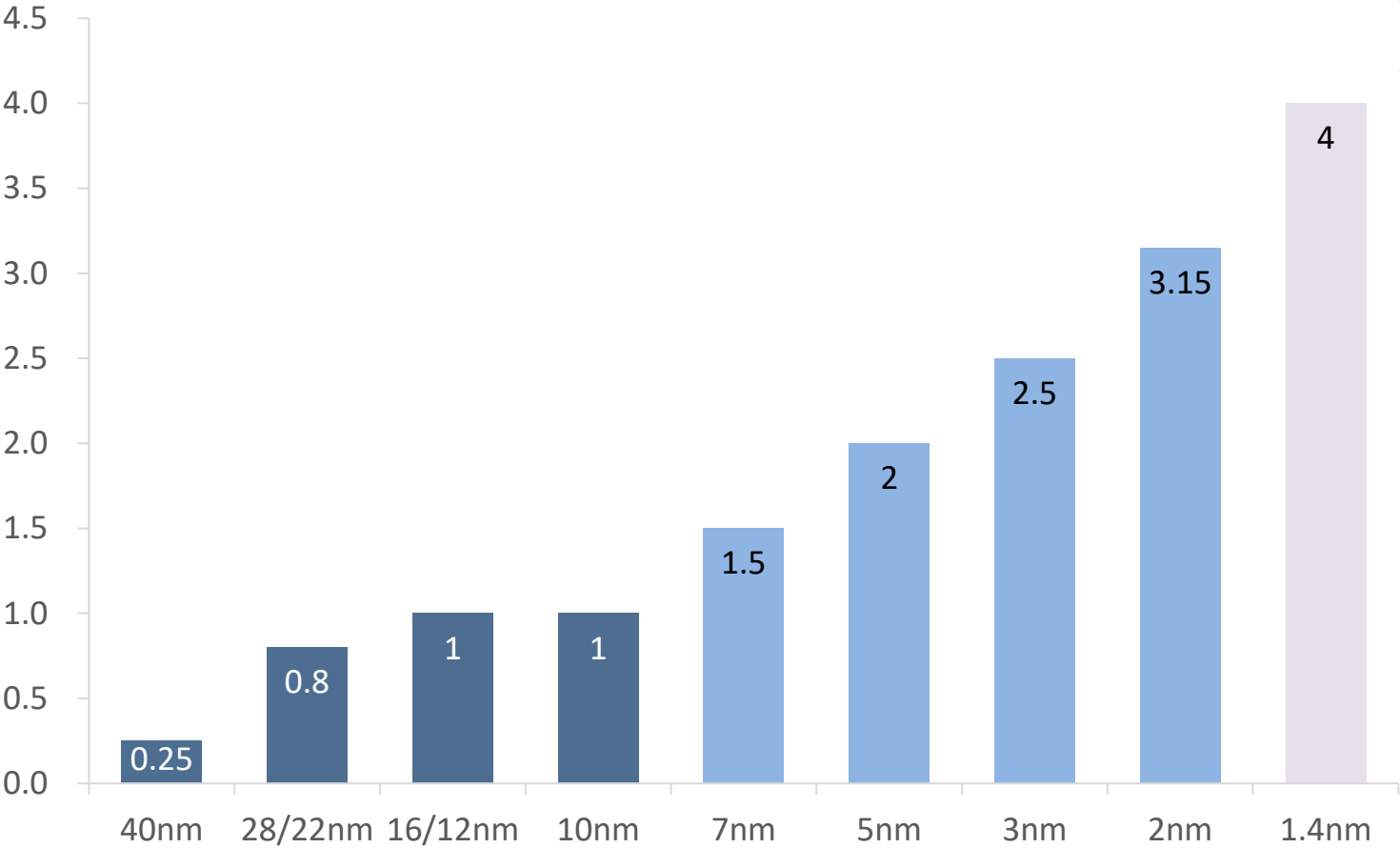


Pillar I: Technology Leadership in Wafer Reclaim



Node Evolution & Reclaim Content

Reclaim Usage



Reclaim Usage

Advanced-node reclaim usage is increasing, with four key specifications upgraded to support higher profit content.

Reclaim Wafer Quality Metrics

Core Quality Indicators

- 1

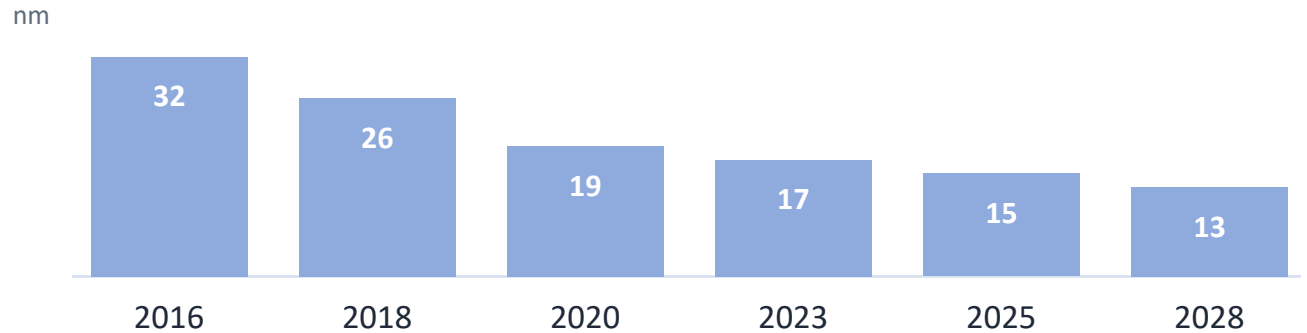
Particle Count & Size
Ensures surface cleanliness for advanced processes.
- 2

Metal Contamination Level
Controls trace metals to protect reliability.
- 3

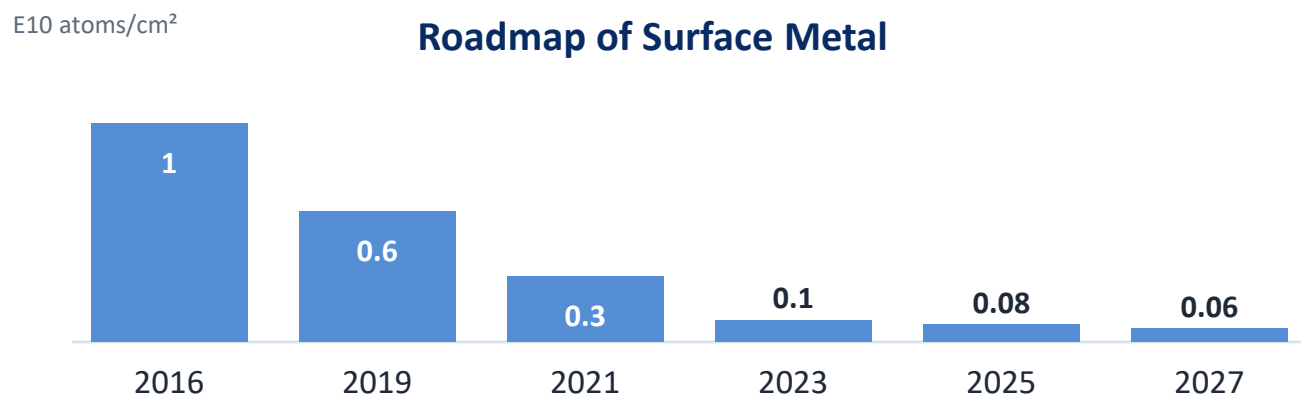
Return Rate Yield
Measures reclaim yield and reuse efficiency.
- 4

Surface Removal Amount
Controls removal depth and surface uniformity.

Roadmap of Particle Size, LLS



Roadmap of Surface Metal



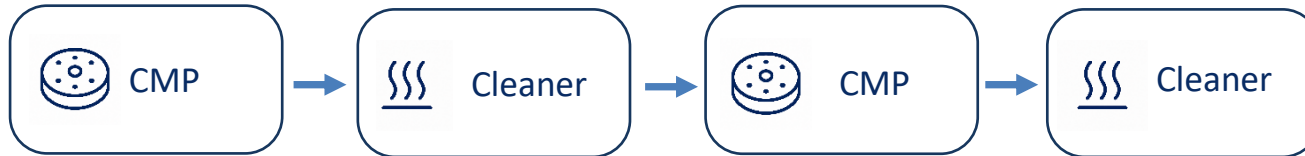
Technology Evolution

Gen1 WIWO CMP



Conventional

Gen2 DIDO CMP



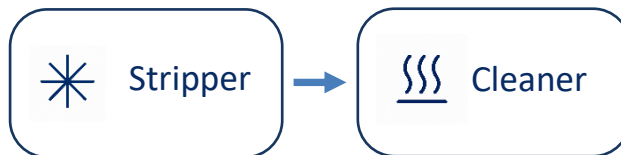
OHT Enabling

Gen3 GDP



High Quality

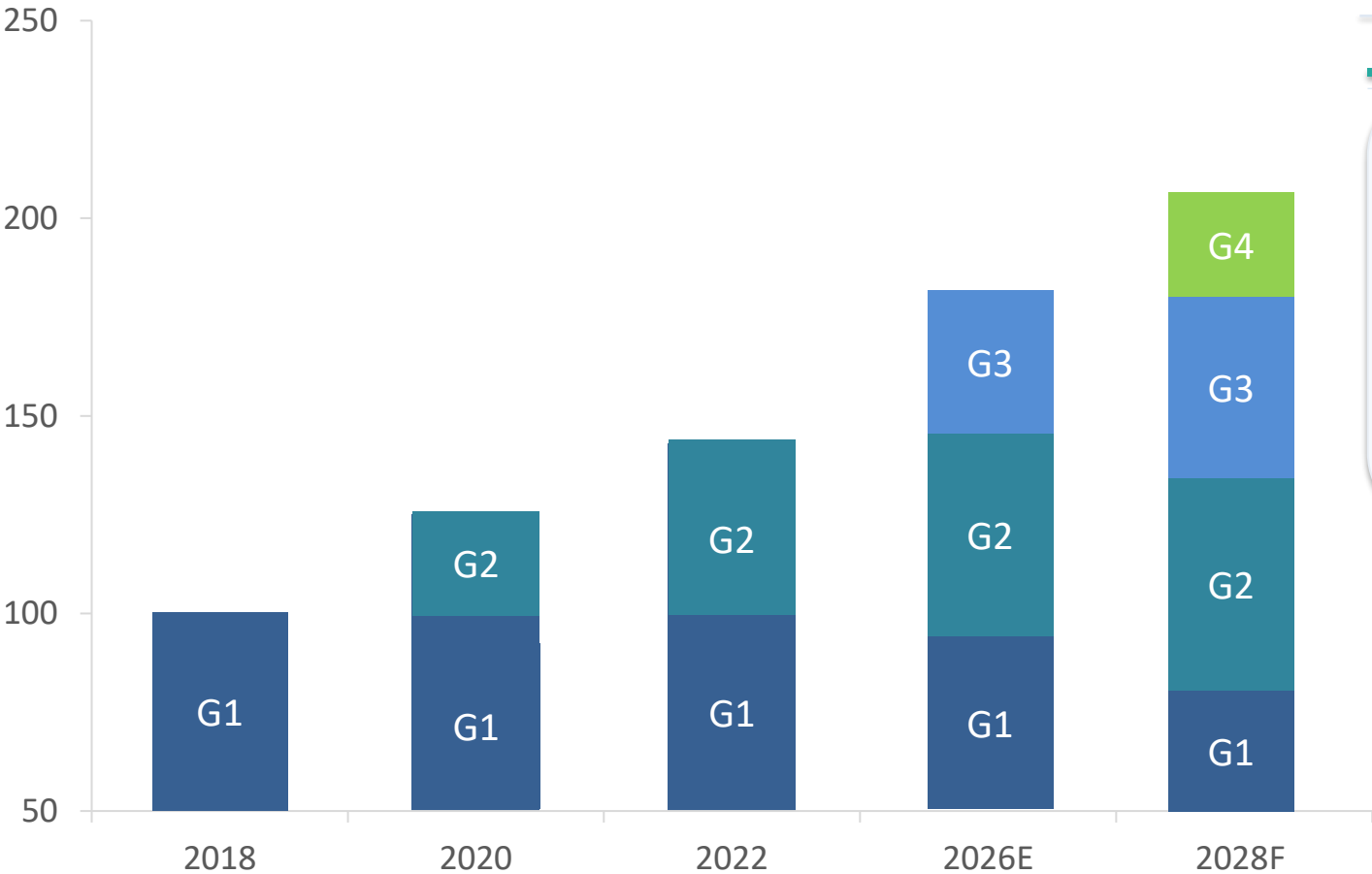
Gen4 AP Stripper



ECO Friendly

Technology Deployment Roadmap

Efficiency Index



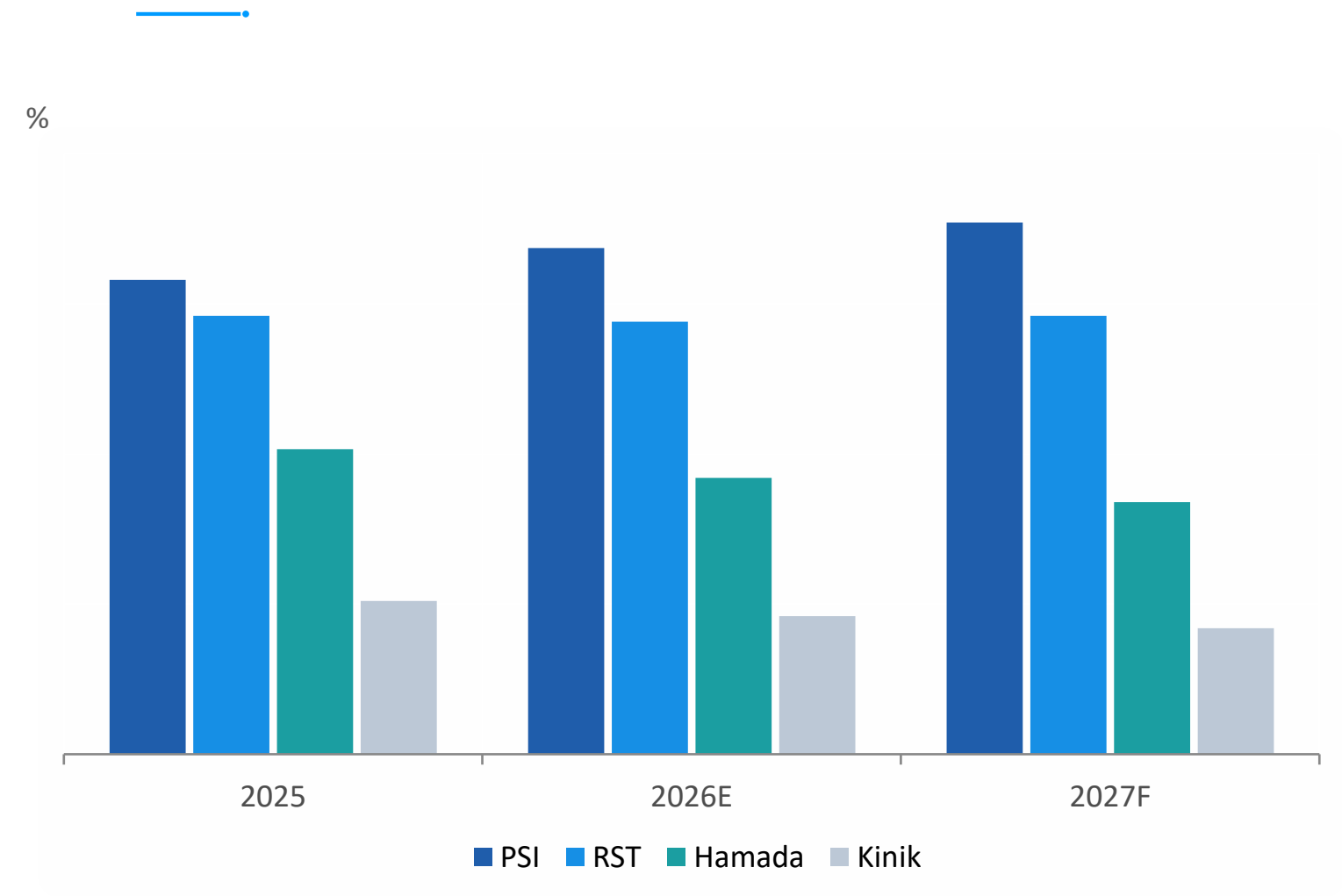
Reclaim Technology Node

Gen 1: Wet-In, Wet-Out CMP
Gen 2: Dry-In, Dry-Out CMP
Gen 3: Grinder and Dry Polisher
Gen 4: Advanced Physical Stripper

Enhancing Efficiency and Effectiveness

- Rising output per depreciation
- Increasing output per employee

WW No.1 PSI continues to Gain Market Share



Market Share

Market size is expanding.

PSI is capturing a larger portion of that growth.

Taiwan's First Aqueous Ammonia Recovery System



Taiwan First

First mover in Taiwan to introduce an aqueous ammonia recovery system



Cradle-to-Cradle

Waste ammonia → Recovery → Industrial-grade ammonia → Reuse



Carbon Reduction

Expected annual GHG reduction **over 330k** tons CO₂e/year.



Key Message

Building a Cradle-to-Cradle resource loop.

PSI is converting waste ammonia into industrial-grade one, shifting from waste treatment to circular resource reuse.

2025 ESG Highlights

Theme	2025 Highlights
 Resource Efficiency	• >0.88m kWh electricity saved • 57% process water recycling • 96% waste recycling
 Governance & Climate Action	• CDP Climate Change: Grade B • Taiwan Sustainability Rating: Grade A • Governance Evaluation: Top 6–20%
 People & Sustainable Growth	• Pension contribution: 6% → 8% • Employee stock trust contribution: 50% • ESG embedded in PSI's 4S strategy

Key Message

Operational efficiency supports resilience

Governance discipline strengthens trust

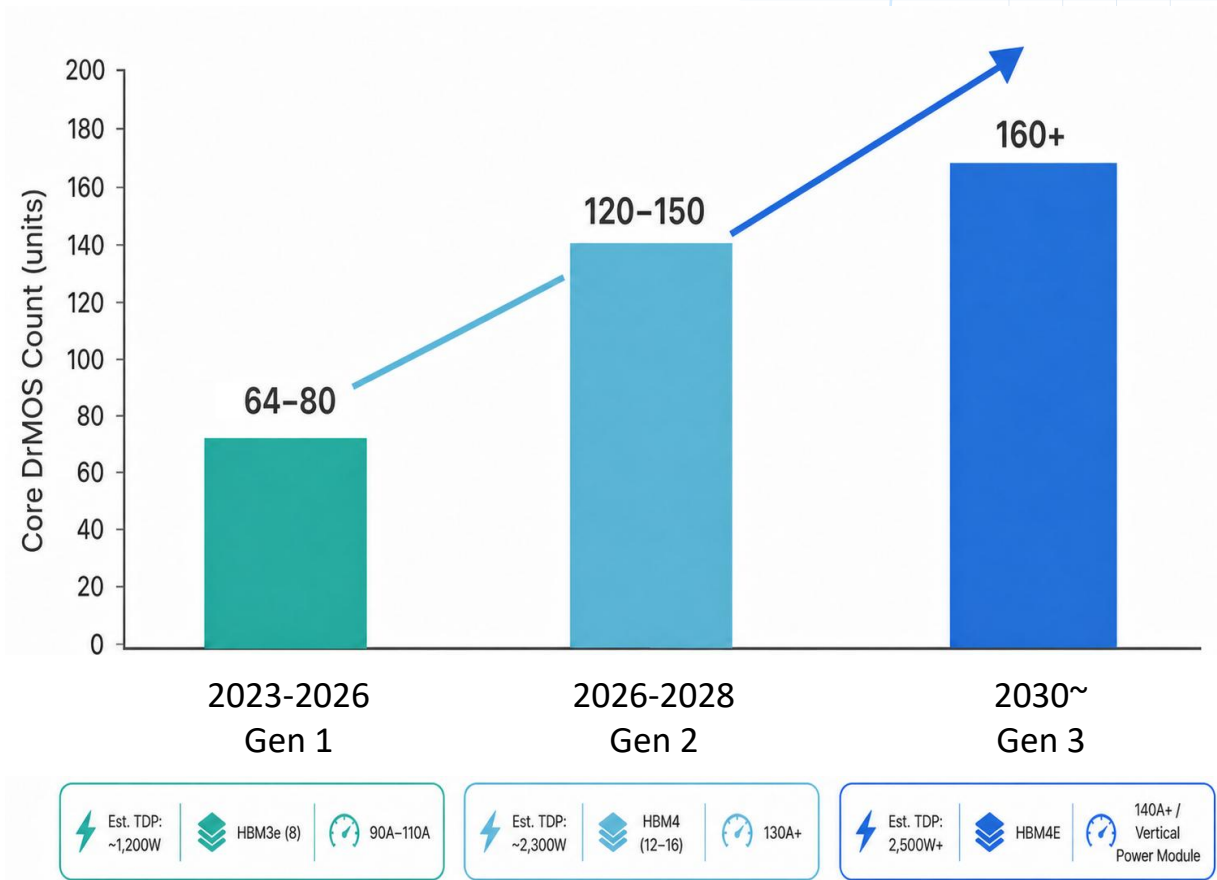
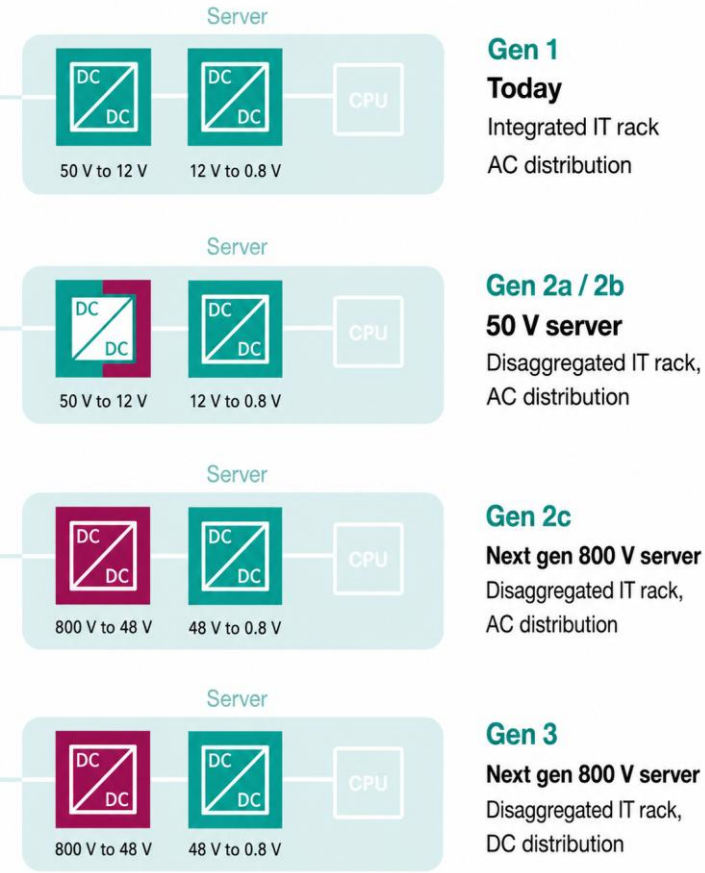
People investment supports long-term growth



Pillar II: The Renaissance of Wafer Thinning

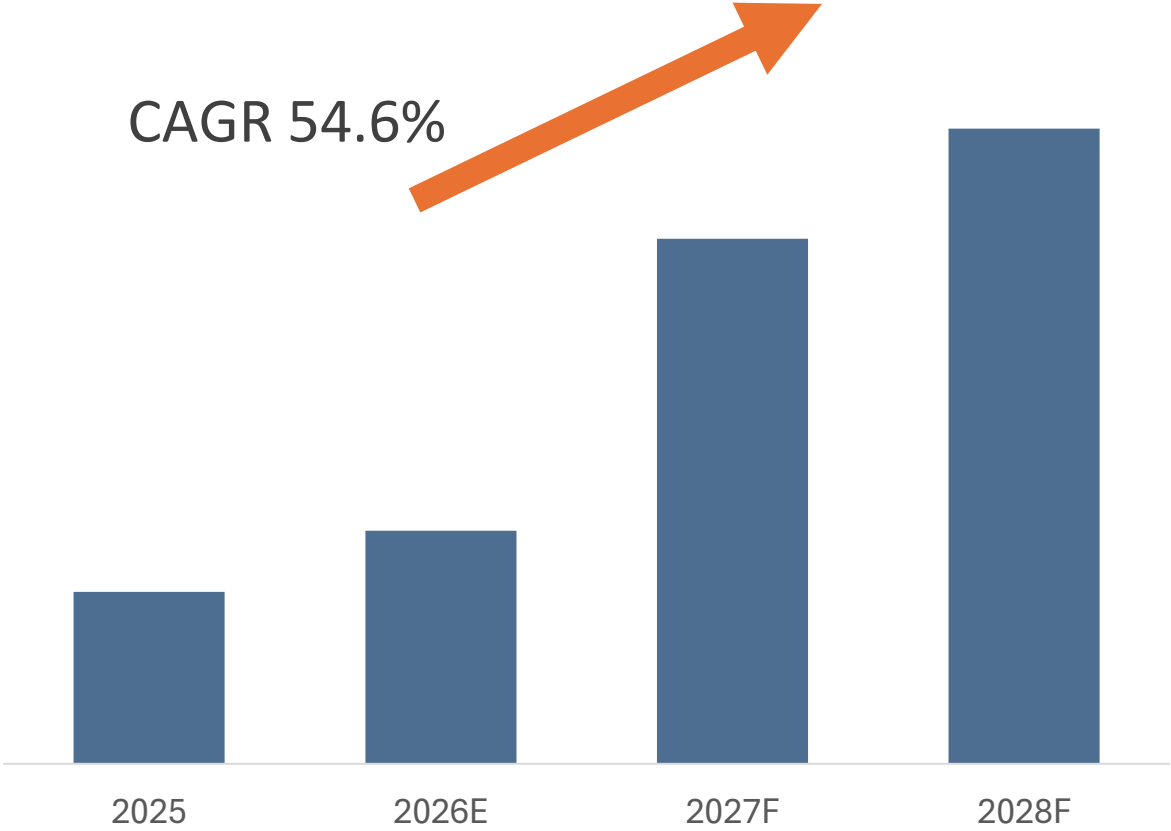


DRMOS Count for AI Trend



IDM DRMOS Trend

KWPM



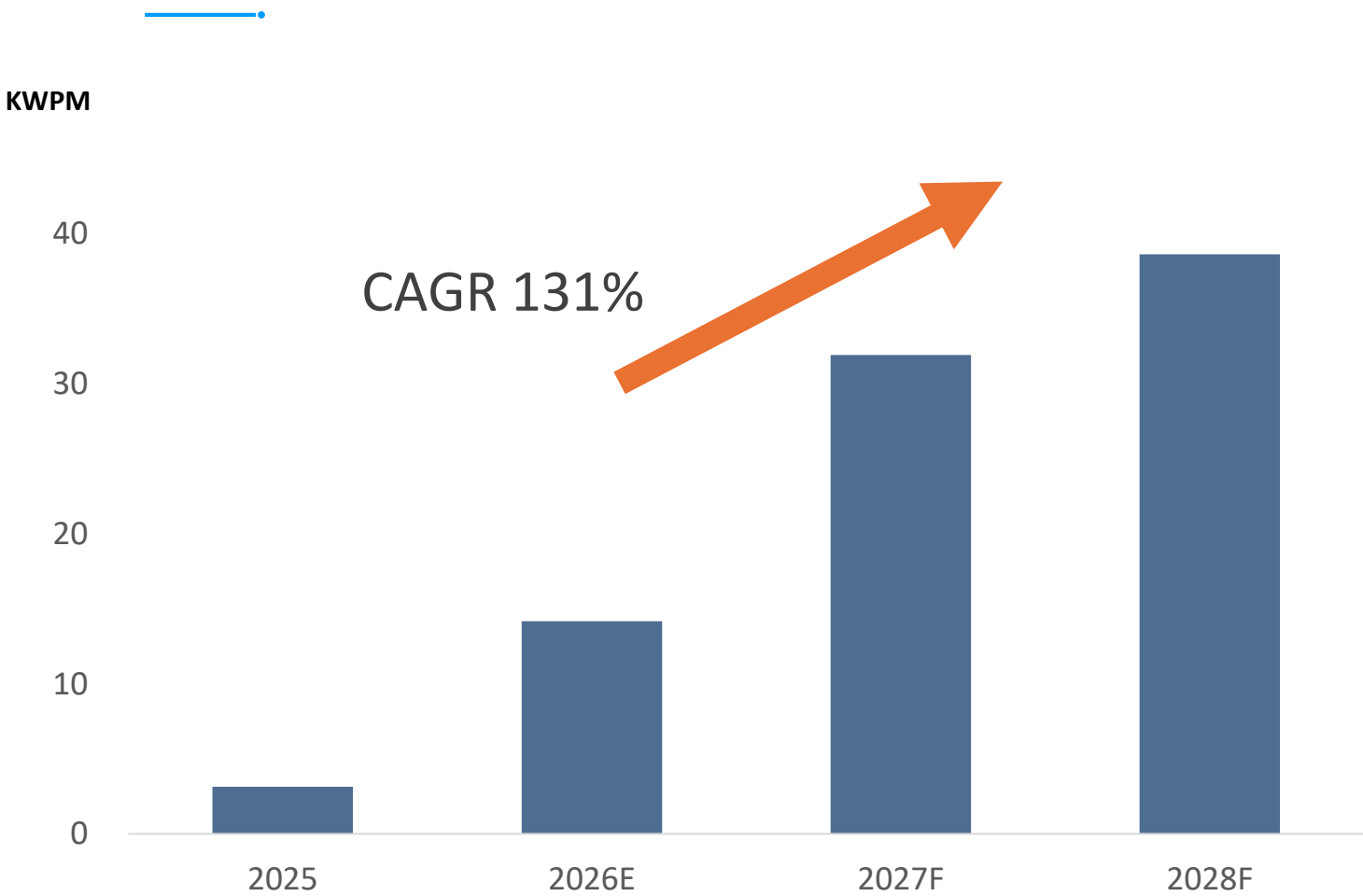
Key message

AI Server Growth

GROWING TAM

Higher GPU servers build-out drives demand for AI infrastructure, POWER management DRMOS.

PSI Power DRMOS Wafer Starts

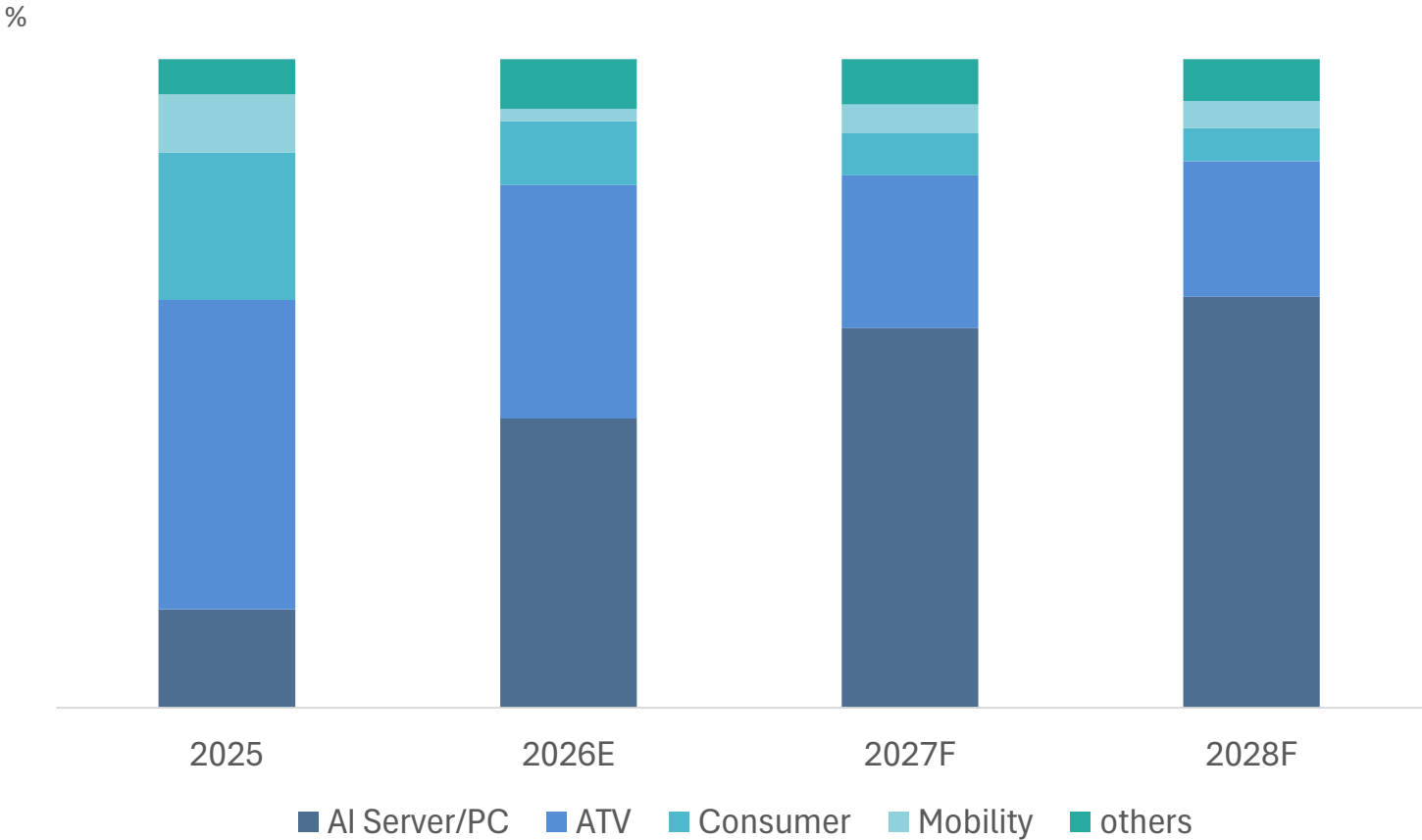


Key message

AI server power upgrades are accelerating Power DRMOS wafer starts and driving thinner (50um-32um), higher-value Taiko process demand.

Driving outsized growth via share gains within an accelerating TAM.

AI Driving PSI Thinning Higher Revenue Mix



Key message

CAGR 45%

AI Server and ATV are expected to account for 63% and 21% of revenue mix by 2028F, supporting margin is expected to double.



Pillar III: **A**dvanced **M**aterial **S**olutions

AMS for Dummy Die / Thermal Dissipation / Warpage Control

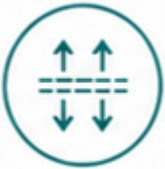


AMS for Dummy / Thermal / Warpage

Si

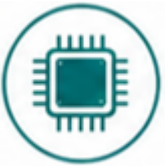
Si – Dummy Die

Foundational Semiconductor Material



1) Mature & Scalable

- Large-area wafer growth
- Cost-effective, abundant, and well-established manufacturing.



2) Excellent Semiconductor

- High carrier mobility ($\sim 1350 \text{ cm}^2/\text{V}\cdot\text{s}$)
- Ideal for high-speed, low-power electronics.



3) Moderate Bandgap

- Bandgap $\sim 1.12 \text{ eV}$ (indirect)
- Enables efficient electronic and optoelectronic devices.



4) Good Thermal Properties

- Thermal conductivity $\sim 150 \text{ W/m}\cdot\text{K}$
- Stable up to $\sim 600^\circ\text{C}$ in inert environments.

SiC

SiC – Thermal Dissipation

High-Performance Material



1) Better Thermal Conductivity

- $260\text{--}450 \text{ W/m}\cdot\text{K}$
- $\sim 2\text{--}3\times$ higher than Si



2) Mechanical Strength

- Mohs hardness ~ 9.2
- $\sim 1.3\times$ stronger than Si



3) Optical Transmission

- SiC: optimal at $0.4\text{--}2 \mu\text{m}$
- Strong and durable



4) High Breakdown Field

- $\sim 10\times$ higher than Si
- Enables a thinner drift layer.

Al₂O₃

Al₂O₃ – Warpage Control

Advanced Ceramic Material



1) Single-Crystal Al₂O₃

- Sapphire-based mono substrate
- Suitable for laser de-bonding



2) Mechanical Hardness

- Excellent wear and abrasion resistance
- High strength and rigidity



3) Thermal Stability

- Melting point $\sim 2072^\circ\text{C}$
- Good dimensional stability

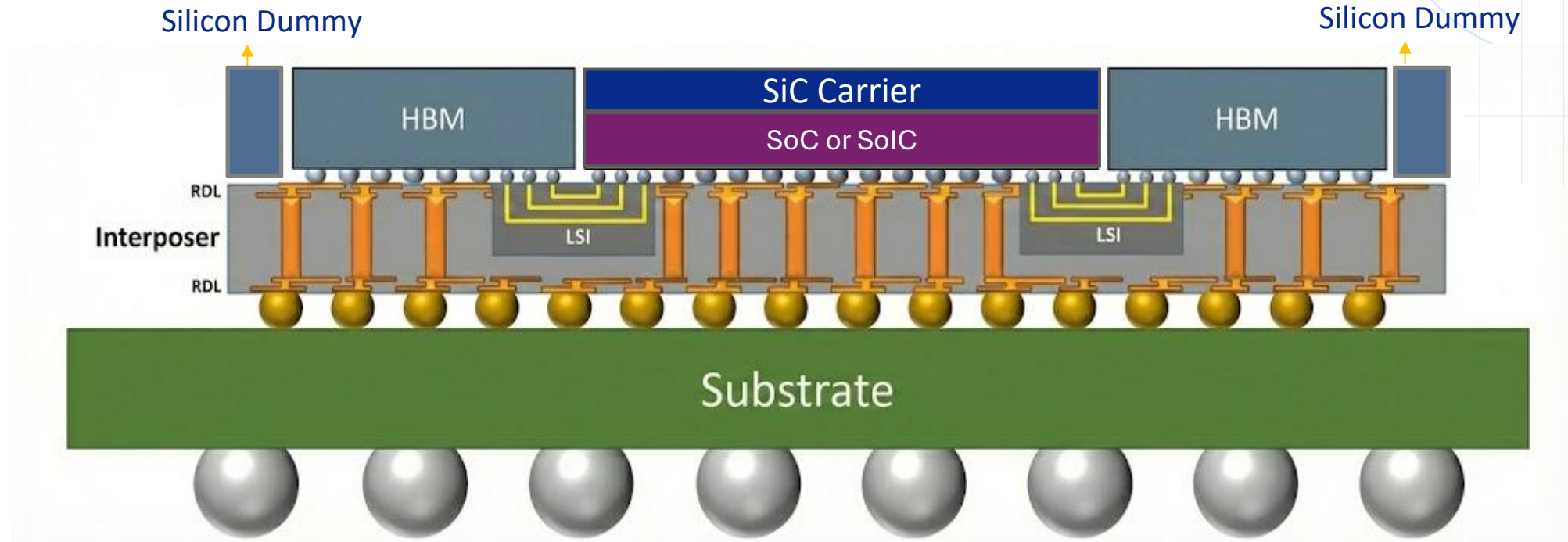


4) Chemical Resistance

- Strong oxidation resistance
- Suitable for harsh environments

AMS- SiC for Thermal Dissipation / Si for Dummy Filler

- Using Si dummy filler to enhance structural stability and packaging consistency.
- Substituting Si carriers with SiC to optimize thermal dissipation efficiency.
- Adopting Al_2O_3 ceramic base to improve warpage control in substrate.



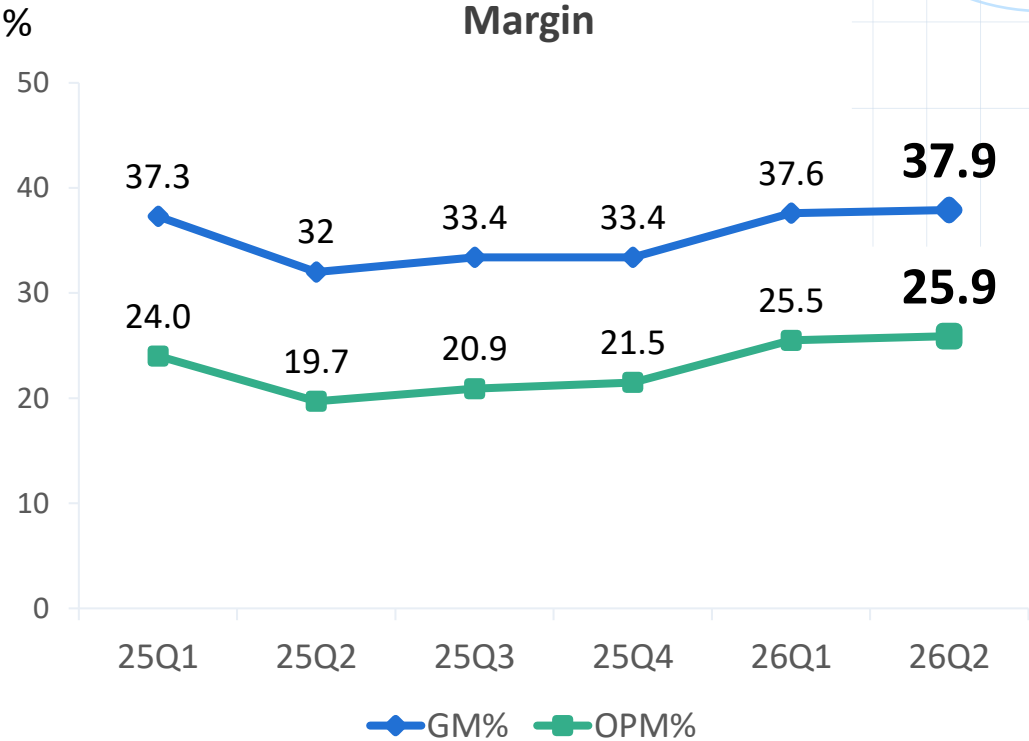
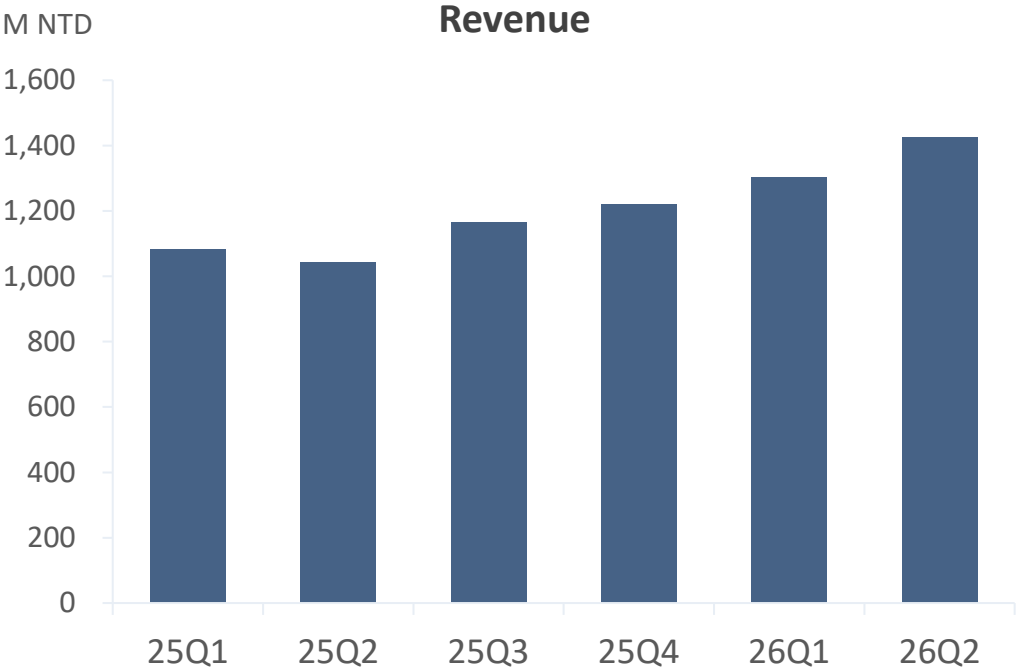


Financial Performance



26Q2 Financial Highlights – Hit the Highest

Revenue	GPM	OPM
NT\$ 1,427M	37.9%	25.9%





Key Takeaways



Key Takeaways



- PSI is benefitted from AI's booming semiconductor demand with a high growth cycle from frontend advanced node to backend advanced packaging.
- PSI is leading through three strategic pillars: innovative reclaim, uplifting thinning, advanced materials.
- PSI's long standing competitive moats are built on technologies in process quality, operation efficiency and environmental sustainability.



<https://www.psi.com.tw>
ir@psi.com.tw

